|  |  |  |
| --- | --- | --- |
|  |  | http://www.minalogic.com/sites/default/files/image3_2.jpg |

## Open Innovation day with Infineon

**Putting a new (inter)face on your**

**relationship with technology**

## Shake up the Open Innovation Day HMI at Graz with Infineon

**Wednesday March 27th, 2019 from 9:00 am to 5:30 pm  
Messe Congress Graz, Graz (Austria)**

**REGISTRATION AND APPLICATION FORM**

**> Company**

|  |  |
| --- | --- |
| Company Name: |  |
| Website address: |  |

**> Contact Person**

|  |  |
| --- | --- |
| Name: |  |
| First Name |  |
| E-mail: |  |
| Mobile Phone: |  |

**> Membership**

Are you member of a Silicon Europe Alliance cluster? Yes  No

If yes, which one?

|  |  |  |  |
| --- | --- | --- | --- |
| BCS (NL) | Distretto G&HT (IT) | DSP Valley (BE) | GAIA (ES) |
| High Tech NL (NL) | MESAP (IT) | MIDAS (EI) | Minalogic (FR) |
| SCS (FR) | Silicon Alps (AT) | Silicon Saxony (DE) | TechWorks (UK) |

Are you member of another cluster? ………………………………………………………………………………..

**> Description of your activities**

|  |
| --- |
|  |

**> Please describe in a few words the level of maturity of your innovation / service / product:**

|  |
| --- |
|  |

**> Areas of interest in HMI innovation: please check the appropriate box(es)**

|  |  |  |  |
| --- | --- | --- | --- |
| 1 | 2 | 3 | 4 |
| Audio sensing / general | Audio sensing / Audio recording | Audio sensing / Voice recognition | Audio sensing / acoustic communication |
|  |  |  |  |

|  |  |  |  |
| --- | --- | --- | --- |
| 5 | 6 | 7 | 8 |
| Environmental sensing / general | Environmental sensing / Emissions measurements | Gesture control | Radar Sensing |
|  |  |  |  |

|  |  |  |  |
| --- | --- | --- | --- |
| 9 | 10 | 11 | 12 |
| Vital sensing | 3D camera-based time-of-flight applications for next-generation scanning | sensing, identification and tracking capabilities, ideally augmented through sensor fusion | Any Other Technologies regarding HMI innovation |
|  |  |  |  |

**> Description of your unique expertise and know-how according to your choice(s)**

|  |
| --- |
|  |

**> Customers**

|  |
| --- |
|  |

**> Key words**

|  |  |
| --- | --- |
|  |  |
|  |  |
|  |  |
|  |  |

**> What kind of cooperation do you expect from Infineon?**

Exchanging with Infineon on technology/product/application questions/ideas

Joint innovation/research project to develop technology/product/application

Building-up and promoting joint system offering to the market (joint go-to-market)

Other (please specify): ………………………………………………………………………………

**> Have you ever interacted with Infineon before?**

Yes  No

If yes, please give a short description and your contact person(s) at Infineon

|  |
| --- |
|  |

**> Comments**

|  |
| --- |
|  |

**Please fill in this Application Form and submit it to your cluster or to Silicon Alps**

**by Feb 12, 2019**

#### Application process

Companies or research institutes wanting to participate, are kindly requested to fill in the registration and application form and send it back to the respective cluster contact.

Please send your application directly to Ruth Aigner ([ruth.aigner@silicon-alps.at](mailto:ruth.aigner@silicon-alps.at)) if you are not a member of the [Silicon Europe partners](https://www.silicon-europe.eu/partners/cluster-partners/).

The [Silicon Europe](https://www.silicon-europe.eu/) clusters, together with Infineon, will then **make a selection** of companies and research institutes and the **selected ones** will be **formally invited to participat**e in the Open Innovation Day *Only the companies and research organizations invited to participate, will have to pay the participation fee*.